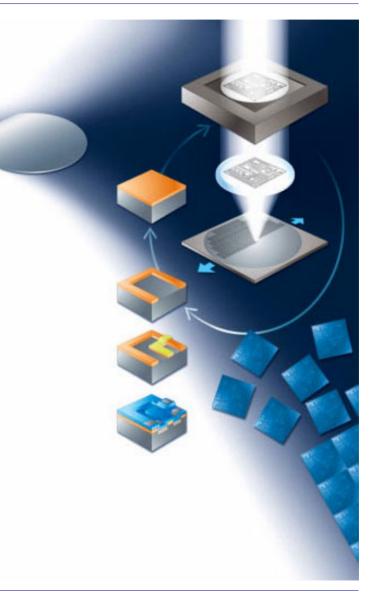


Carl Zeiss Microelectronic Systems GmbH *Enabling the Nano-Age World*

AIMS[™] EUV Development Design Study

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*Carl Zeiss SMT AG Litho Division ™: AIMS is a trademark of Carl Zeiss



What is AIMS[™]?

4 An actinic optical technique to emulate any given stepper or scanner.

What is AIMS[™] good for?

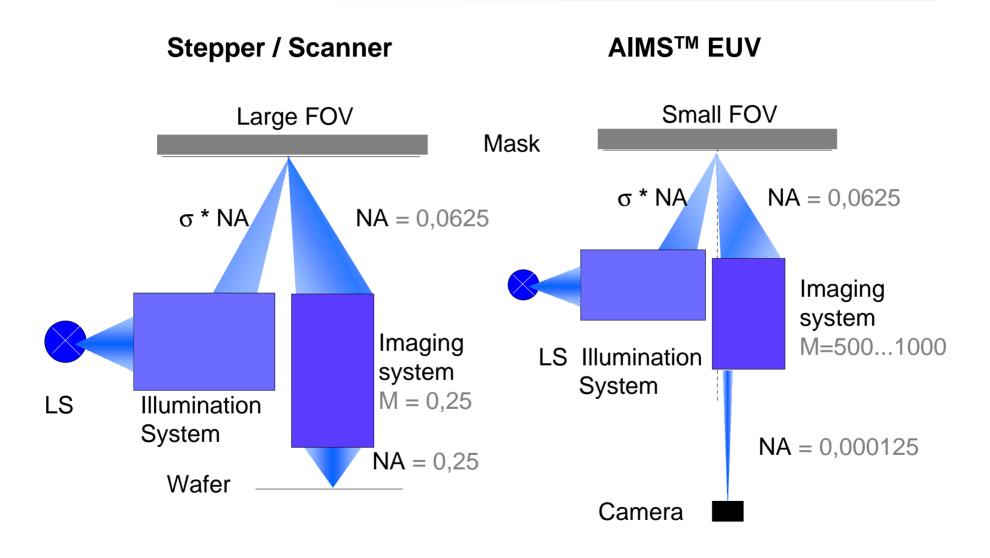
4 Actinic optical printability analysis of reticle defects, repairs and critical areas on all kinds of reticles without the need of stepper prints.

AIMS[™] Applications

- 4 Mask development
- **4** Defect review and disposition
- **4** Repair verification
- 4 Mask quality analysis

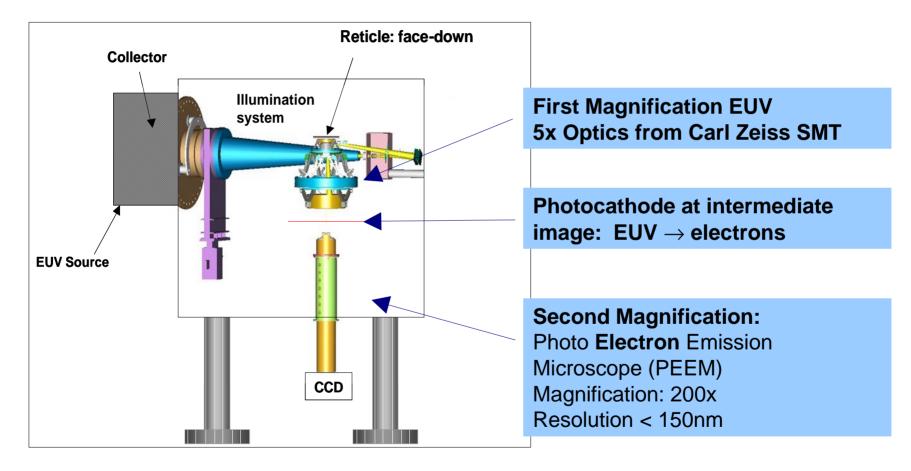
Comparison Stepper vs. AIMS™







"AIMS[™] EUV lite"



AIMS[™] EUV lite: Key specifications



Optics

Reticle stage

- Ø Face down
- Ø Option:

Interferometer stage

Carl Zeiss AIMS[™] measurement and analysis software

- $\ensuremath{\varnothing}$ Recipe operation, up-date of inspection files
- $\ensuremath{\varnothing}$ Connectivity: link to all major inspection tools



Differences to current EUV Scanner Design

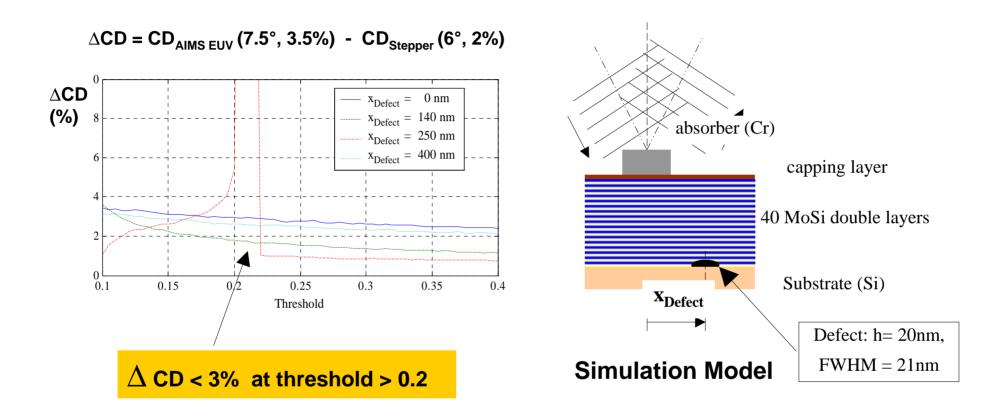
	AIMS-EUV lite	Scanner
		α-tool
Chief ray angle	7.5°	6°
(CRA)	due to modified MET	
Bandwidth	3.5%	2%
	due to 2 mirror optics	

Impact on AIMS[™] performance ?

4 Detection sensitivity of nano-particles in mask blanks? 4 CD variation due to different CRA?

Simulate AIMS[™] EUV performance for different CRA and bandwidths





Carl Zeiss AIMS[™] EUV lite with CRA = 7.5° and 3.5% bandwidth

4 No impact on sensitivity for particle detection in EUV multilayers and blanks

4 Systematic CD difference of 3 % a compensation by calibration

* Simulations made by P. Evanschitzky / A. Erdmann at Fraunhofer IISB Erlangen / Germany



Zeiss AIMS EUV lite

4 All key components are state-of-the art, available and tested

4 Short lead time and price attractive tool

4 Blank and patterned EUV mask development and qualification

4 Fits requirements for 45 and 32 nm node